

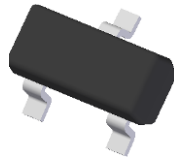
Features

- Ideally Suited for Automatic Insertion
- Epitaxial Planar Die Construction
- Complementary PNP Types Available (BC807)
- For switching and AF Amplifier Applications
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **Automotive-Compliant Parts Are Available Under Separate Datasheet ([BC817-16Q_40Q](#))**

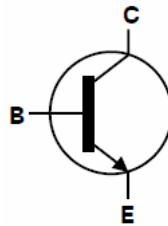
Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 Ⓜ3
- Weight 0.008 grams (Approximate)

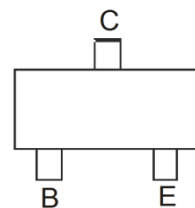
SOT23



Top View



Device Symbol



Top View
Pin-Out

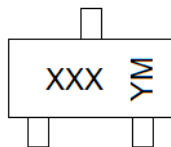
Ordering Information (Note 4)

| Product | Compliance | Marking | Reel Size (inches) | Tape Width (mm) | Quantity Per Reel |
|--------------|------------|---------|--------------------|-----------------|-------------------|
| BC817-16-7-F | AEC-Q101 | K6A | 7 | 8 | 3,000 |
| BC817-25-7-F | AEC-Q101 | K6B | 7 | 8 | 3,000 |
| BC817-40-7-F | AEC-Q101 | K6C | 7 | 8 | 3,000 |

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information

SOT23



XXX = Product Type Marking Code (See Table Above)
 YM = Date Code Marking
 Y = Year (ex: C = 2015)
 M = Month (ex: 9 = September)

Date Code Key

| Year | 2015 | 2016 | 2017 | 2018 | 2019 | 2020 | 2021 | 2022 | 2023 | 2024 | 2025 | 2026 |
|------|------|------|------|------|------|------|------|------|------|------|------|------|
| Code | C | D | E | F | G | H | I | J | K | L | M | N |

| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
|-------|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|
| Code | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | O | N | D |

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit |
|---------------------------|------------------|-------|------|
| Collector-Base Voltage | V _{CB0} | 50 | V |
| Collector-Emitter Voltage | V _{CEO} | 45 | V |
| Emitter-Base Voltage | V _{EBO} | 5.0 | V |
| Collector Current | I _C | 0.5 | A |
| Peak Collector Current | I _{CM} | 1.0 | A |
| Peak Base Current | I _{BM} | 200 | mA |

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

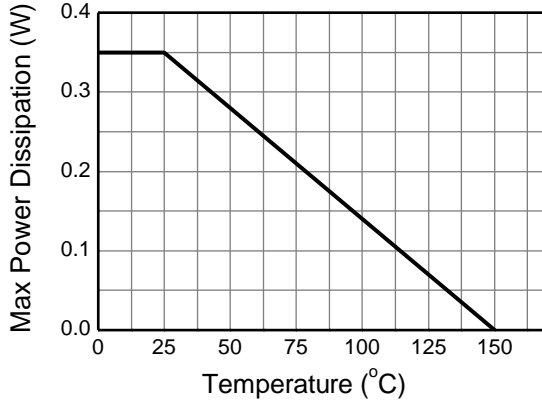
| Characteristic | Symbol | Value | Unit |
|---|-----------------------------------|-------------|------|
| Power Dissipation | P _D | (Note 5) | 310 |
| | | (Note 6) | 350 |
| Thermal Resistance, Junction to Ambient | R _{θJA} | (Note 5) | 403 |
| | | (Note 6) | 357 |
| Thermal Resistance, Junction to Leads | R _{θJL} | 350 | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -65 to +150 | °C |

ESD Ratings (Note 8)

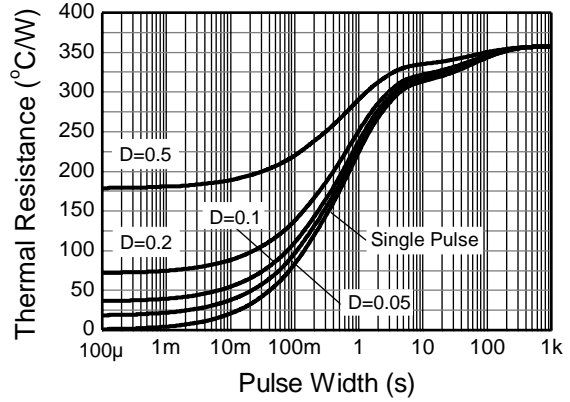
| Characteristic | Symbol | Value | Unit | JEDEC Class |
|--|---------|-------|------|-------------|
| Electrostatic Discharge - Human Body Model | ESD HBM | 8,000 | V | 3B |
| Electrostatic Discharge - Machine Model | ESD MM | 400 | V | C |

- Notes:
5. For a device mounted on minimum recommended pad layout FR-4 PCB with high coverage of single sided 1oz copper; device is measured under still air conditions whilst operating in a steady-state.
 6. Same as Note 5, except mounted on 15mm x 15mm 1oz copper.
 7. Thermal resistance from junction to solder-point (at the end of the collector lead).
 8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

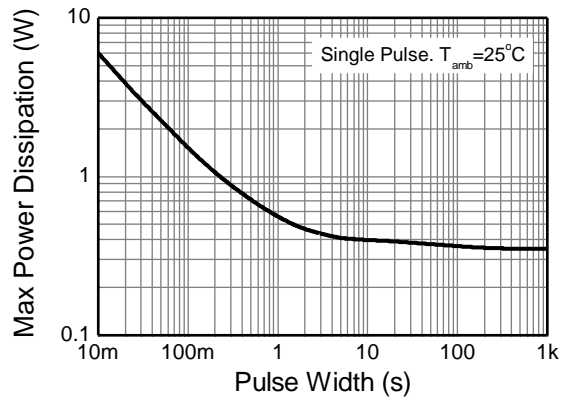
Thermal Characteristics and Derating Information



Derating Curve



Transient Thermal Impedance



Pulse Power Dissipation

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | | Symbol | Min | Typ | Max | Unit | Test Condition |
|---|----------------------------------|----------------------|-------------------|-----|-------------------|----------|---|
| Collector-Base Breakdown Voltage | | BV _{CBO} | 50 | — | — | V | I _C = 100μA |
| Collector-Emitter Breakdown Voltage | | BV _{CEO} | 45 | — | — | V | I _C = 10mA |
| Emitter-Base Breakdown Voltage | | BV _{EBO} | 5 | — | — | V | I _C = 100μA |
| Collector-Emitter Cut-Off Current | | I _{CES} | — | — | 100 5.0 | nA μA | V _{CE} = 45V V _{CE} = 25V, T _J = +150°C |
| Emitter-Base Cut-Off Current | | I _{EBO} | — | — | 100 | nA | V _{EB} = 5.0V |
| DC Current Gain (Note 9) | BC817-16 BC817-25 BC817-40 | h _{FE} | 100 160 250 | — | 250 400 600 | — | V _{CE} = 1.0V, I _C = 100mA |
| | BC817-16 BC817-25 BC817-40 | | 60 100 170 | | — | | |
| Collector-Emitter Saturation Voltage (Note 9) | | V _{CE(SAT)} | — | — | 0.7 | V | I _C = 500mA, I _B = 50mA |
| Base-Emitter Voltage (Note 9) | | V _{BE} | — | — | 1.2 | V | V _{CE} = 1.0V, I _C = 300mA |
| Gain Bandwidth Product | | f _T | 100 | — | — | MHz | V _{CE} = 5.0V, I _C = 10mA, f = 50MHz |
| Collector-Base Capacitance | | C _{CBO} | — | — | 12 | pF | V _{CB} = 10V, f = 1.0MHz |

Note: 9. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

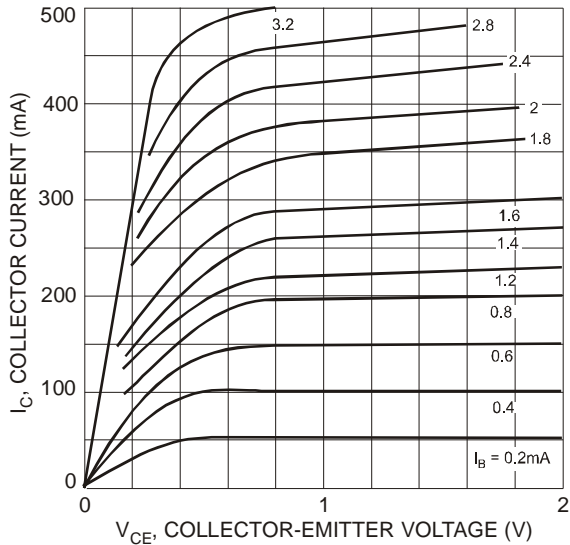


Figure 1 Typical Collector Current vs. Collector-Emitter Voltage

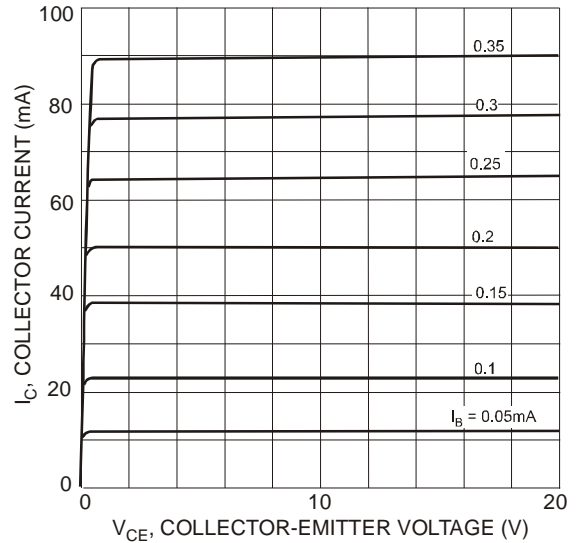


Figure 2 Typical Collector Current vs. Collector-Emitter Voltage

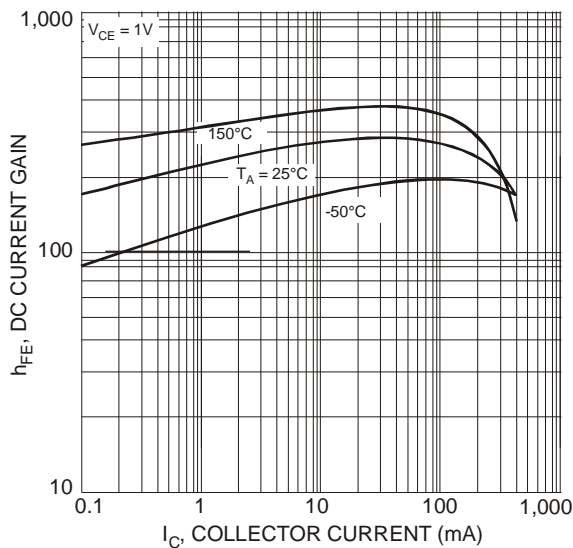


Figure 3 Typical DC Current Gain vs. Collector Current

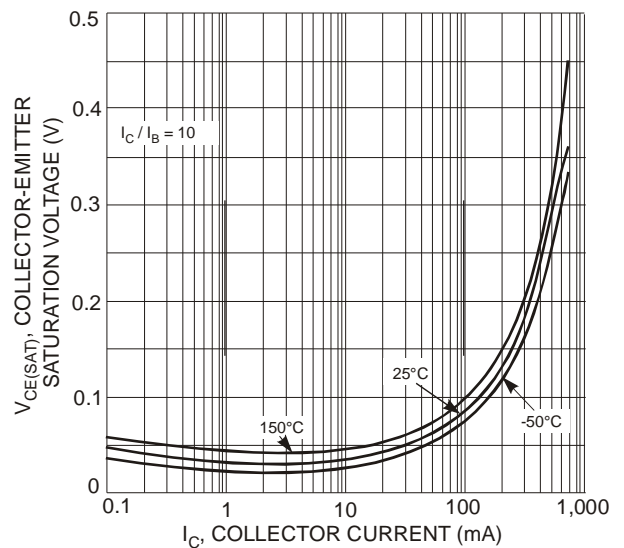


Figure 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

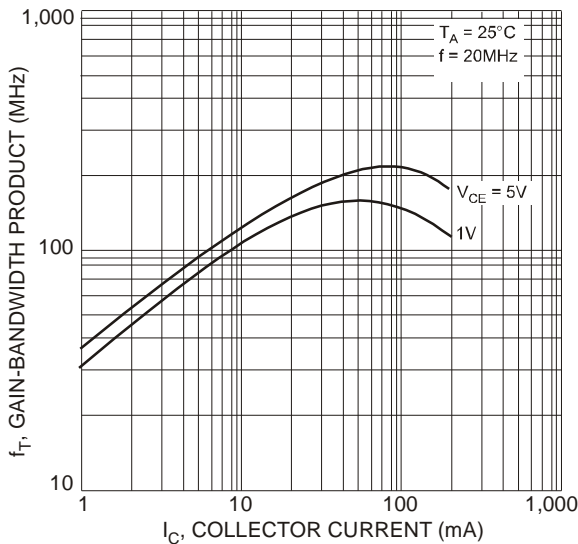
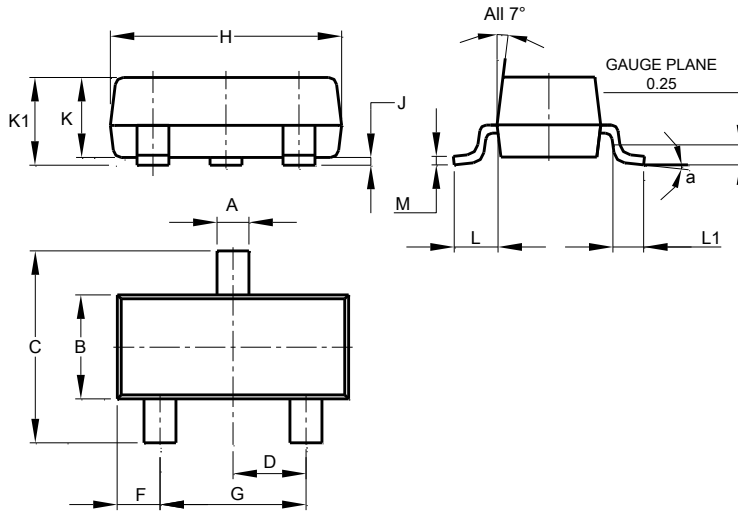


Figure 5 Gain-Bandwidth Product vs. Collector Current

Package Outline Dimensions

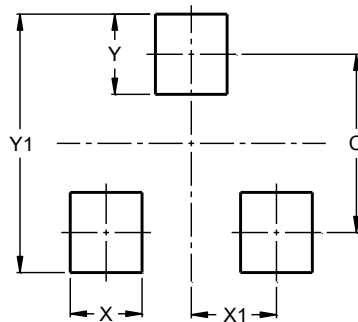
Please see AP02001 at http://www.diodes.com/_files/datasheets/ap02001.pdf for the latest version.



| SOT23 | | | |
|----------------------|-------|-------|-------|
| Dim | Min | Max | Typ |
| A | 0.37 | 0.51 | 0.40 |
| B | 1.20 | 1.40 | 1.30 |
| C | 2.30 | 2.50 | 2.40 |
| D | 0.89 | 1.03 | 0.915 |
| F | 0.45 | 0.60 | 0.535 |
| G | 1.78 | 2.05 | 1.83 |
| H | 2.80 | 3.00 | 2.90 |
| J | 0.013 | 0.10 | 0.05 |
| K | 0.890 | 1.00 | 0.975 |
| K1 | 0.903 | 1.10 | 1.025 |
| L | 0.45 | 0.61 | 0.55 |
| L1 | 0.25 | 0.55 | 0.40 |
| M | 0.085 | 0.150 | 0.110 |
| a | 0° | 8° | -- |
| All Dimensions in mm | | | |

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/_files/datasheets/ap02001.pdf for the latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| C | 2.0 |
| X | 0.8 |
| X1 | 1.35 |
| Y | 0.9 |
| Y1 | 2.9 |

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